

JC06 Rec'd PCT/PTO 08 JUN 2005

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Date of Deposit: June 8, 2005Case No. 9905/28
Client No. BIF023237/US**UNITED STATES PATENT AND TRADEMARK OFFICE**

| | | |
|------------------------------|---|------------------|
| In re Application of: |) | |
| FOURNEL et al. |) | |
| Serial No.: Not Yet Assigned |) | Examiner: |
| |) | Not Yet Assigned |
| Filing Date: Herewith |) | |
| |) | Group Art Unit: |
| For: METHOD FOR MAKING |) | Not Yet Assigned |
| A STRESSED STRUCTURE |) | |
| DESIGNED TO BE DISSOCIATED |) | |

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Dear Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and
§§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b),
Applicants hereby cite the following references:

| No. | Date of Publication | Patentee/Applicant/Country |
|---|---------------------|----------------------------|
| 5,400,458 | 03/28/1995 | Huber et al. |
| 4,254,590 | 03/10/1981 | Eisele et al. |
| 5,374,564 | 12/20/1994 | Bruel |
| FR 2 681 472 A1 | 03/19/1993 | France |
| WO 00/48238 | 08/17/2000 | PCT |
| EP 1 050 901 A2 | 11/08/2000 | EPO |
| EP 0 410 679 A1 | 07/24/1990 | EPO |
| 101004013 | 07/05/1999 | Japan |
| Feijoo et al., "Prestressing of Bonded Wafers", Proceedings of the 1st International Symposium on Semiconductor Wafer Bonding, Science Technology and Applications, Vol. 92-7, The Electrochemical Society (1992), pp. 230-238. | | |
| Feijoo et al., "Generalized Formula for Curvature Radius and Layer Stresses Caused by Thermal Strain in Semiconductor Multilayer Structures," Appl. Phys. 54(1), 1983, page 83. | | |
| S. Timoshenko, "Analysis of Bi-Metal Thermostats," J. Opt. Soc. Am. 11 (1925), page 233-256. | | |

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08 JUN 2005

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| FORM PTO-1449 | SERIAL NO. Not Yet Assigned | CASE NO. 10538482 990728 (BIF023237/US) |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT | FILING DATE Herewith | GROUP ART UNIT Not Yet Assigned |
| APPLICANTS: FURNEL et al. | | |

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER <small>Number-Kind Code (if known)</small> | DATE | NAME | CLASS/ SUBCLASS | FILING DATE |
|---------------------|----|--|------------|---------------|--------------------|----------------|
| | A1 | 5,400,458 | 03/28/1995 | Huber et al. | | |
| | A2 | 4,254,590 | 03/10/1981 | Eisele et al. | | |
| | A3 | 5,374,564 | 12/20/1994 | Bruehl | | |

FOREIGN PATENT DOCUMENT

| EXAMINER INITIAL | | DOCUMENT NUMBER <small>Number-Kind Code (if known)</small> | DATE | COUNTRY | CLASS/ SUBCLASS S | TRANSLATION YES OR NO |
|---------------------|----|--|------------|---------|-------------------------|--------------------------|
| | A4 | FR 2 681 472 A1 | 03/19/1993 | France | | |
| | A5 | WO 00/48238 | 08/17/2000 | PCT | | |
| | A6 | EP 1 050 901 A2 | 11/08/2000 | EPO | | |
| | A7 | EP 0 410 679 A1 | 07/24/1990 | EPO | | |
| | A8 | 101004013 | 07/05/1999 | Japan | | Abstract only |

| EXAMINER INITIAL | OTHER ART - NON PATENT LITERATURE DOCUMENTS <small>(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.</small> | | | | | |
|---------------------|--|---|--|--|--|--|
| | A9 | Feijoo et al., "Prestressing of Bonded Wafers", Proceedings of the 1st International Symposium on Semiconductor Wafer Bonding, Science Technology and Applications, Vol. 92-7, The Electrochemical Society (1992), pp. 230-238. | | | | |
| | A10 | Feijoo et al., "Generalized Formula for Curvature Radius and Layer Stresses Caused by Thermal Strain in Semiconductor Multilayer Structures," Appl. Phys. 54(1), 1983, page 83. | | | | |
| | A11 | S. Timoshenko, "Analysis of Bi-Metal Thermostats," J. Opt. Soc. Am. 11 (1925), page 233-256. | | | | |

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| EXAMINER | /Elias Ullah/ | DATE CONSIDERED | 11/20/2008 |
|----------|---------------|-----------------|------------|

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /E.U./